

2SB647(A)T
Rev.A May.-2016

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-120	V
Collector to Emitter Voltage	V_{CEO}	2SB647T	-80
		2SB647AT	-100
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current (DC)	I_C	-1.0	A
Collector Current(Pulse)	I_{CP}	-2.0	A
Collector Power Dissipation	P_C	500	mW
Collector Power Dissipation*	* P_C	1.0	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

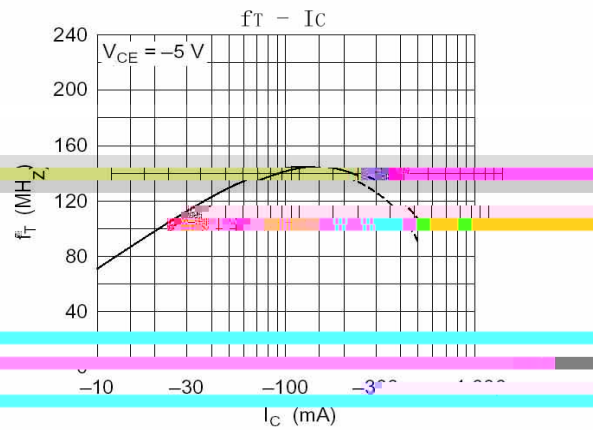
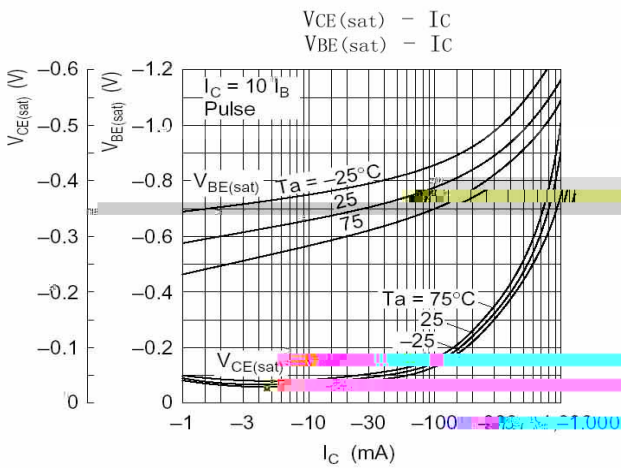
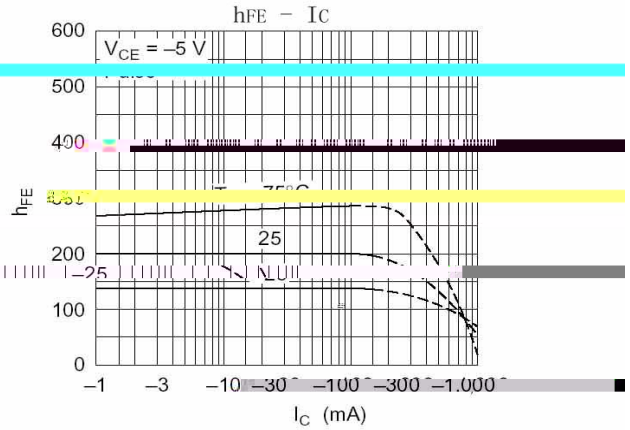
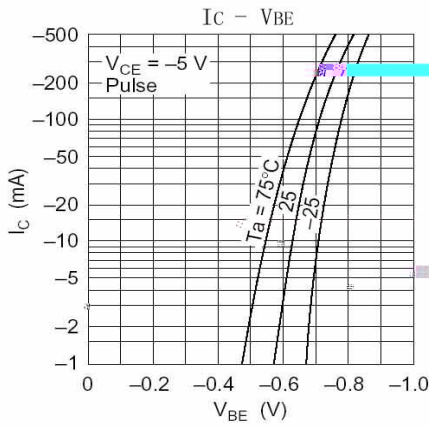
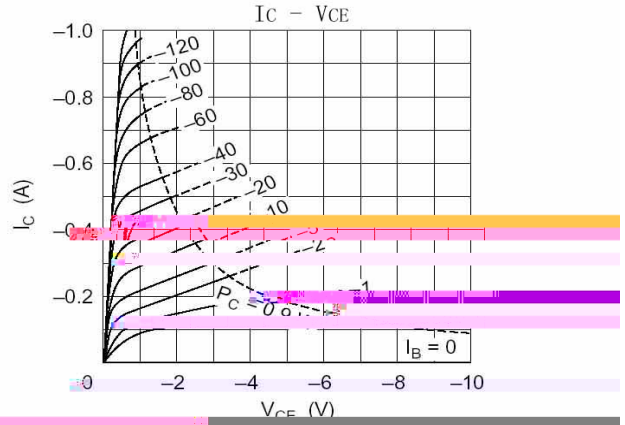
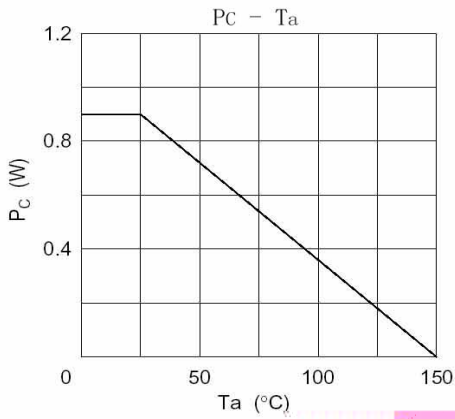
*:mounted on ceramic substrate(250mm²×0.8t).

* 250mm²×0.8t

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=-10\text{ A}$ $I_E=0$	-120			V
Collector to Emitter Breakdown Voltage	V_{CEO}	2SB647T	-80			V
		2SB647AT	-100			
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E=-10\text{ A}$ $I_C=0$	-5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-100\text{V}$ $I_E=0$			-10	A
DC Current Gain	$h_{FE(1)}$	$V_{CE}=-5.0\text{V}$ $I_C=-150\text{mA}$	60		320	
	$h_{FE(2)}$	$V_{CE}=-5.0\text{V}$ $I_C=-500\text{mA}$	30			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-500\text{mA}$ $I_B=-50\text{mA}$			-1.0	V
Base to Emitter Voltage	V_{BE}	$V_{CE}=-5.0\text{V}$ $I_C=-150\text{mA}$			-1.5	V
Transition Frequency	f_T	$V_{CE}=-5.0\text{V}$ $I_C=-150\text{mA}$		140		MHz
Collector Output Capacitance	C_{ob}	$V_{CB}=-10\text{V}$ $I_E=0$ $f=1.0\text{MHz}$		12		pF

/ Electrical Characteristic Curve



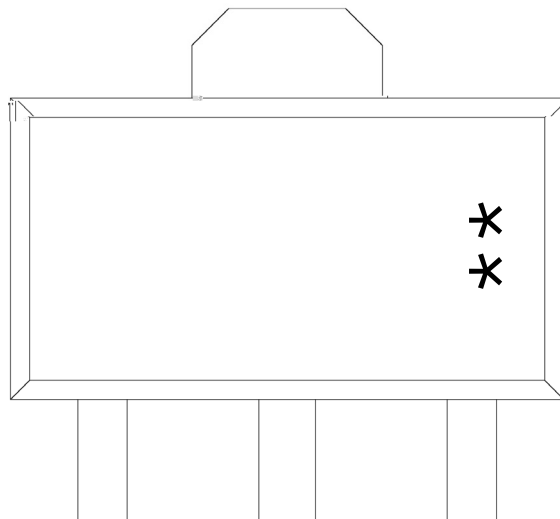
/ Package Dimensions

SOT-89

单位: mm



/ Marking Instructions



H:

47

B: h_{FE}

Note:

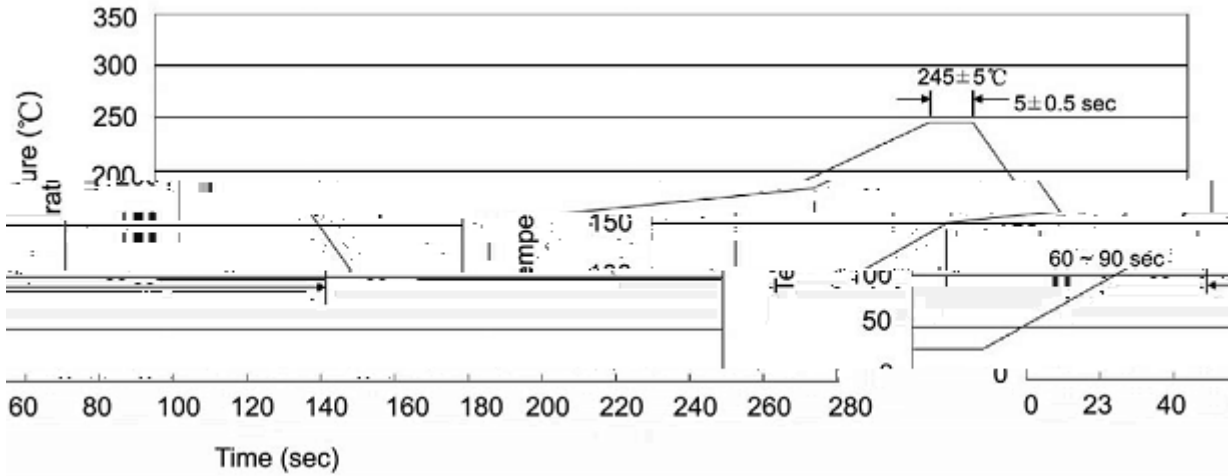
H: Company Code.

47: Product Type.

B: h_{FE} Classifications Symbol

****: Lot No. Code,code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只卷盘	卷盘盒	只盒	盒箱	只箱	盒	箱	

/ Notices